

Electrical Characteristics ($T_A = 25^\circ\text{C}$ Unless otherwise specified.)**Individual Component Characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
INPUT						
V_F	Forward Voltage	$I_F = 20\text{mA}$	–	1.2	1.4	V
C_t	Terminal Capacitance	$V = 0, f = 1\text{kHz}$	–	50	250	pF
OUTPUT						
I_{CEO}	Collector Dark Current	$V_{CE} = 10\text{V}, I_F = 0$	–	–	1	μA
BV_{CEO}	Collector-Emitter Breakdown Voltage	$I_C = 0.1\text{mA}, I_F = 0$	35	–	–	V
BV_{ECO}	Emitter-Collector Breakdown Voltage	$I_E = 10\mu\text{A}, I_F = 0$	6	–	–	V

Transfer Characteristics ($T_A = 25^\circ\text{C}$ Unless otherwise specified.)

Symbol	DC Characteristic	Test Conditions	Min.	Typ.	Max.	Unit
I_C	Collector Current	$I_F = 1\text{mA}, V_{CE} = 2\text{V}$	6	–	75	mA
CTR	Current Transfer Ratio ⁽¹⁾		600	–	7,500	%
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_F = 20\text{mA}, I_C = 5\text{mA}$	–	0.8	1	V
f_C	Cut-Off Frequency	$V_{CE} = 5\text{V}, I_C = 2\text{mA}, R_L = 100\Omega, -3\text{dB}$	1	6	–	KHz
t_r	Response Time (Rise)	$V_{CE} = 2\text{V}, I_C = 10\text{mA}, R_L = 100\Omega$	–	60	300	μs
t_f	Response Time (Fall)		–	53	250	μs

Isolation Characteristics

Symbol	Characteristic	Test Conditions	Min.	Typ.	Max.	Units
V_{ISO}	Input-Output Isolation Voltage	$f = 60\text{Hz}, t = 1\text{ min}, I_{I-O} \leq 2\mu\text{A}$	5000	–	–	Vac(rms)
R_{iso}	Isolation Resistance	DC500V 40~60% R.H.	5×10^{10}	1×10^{11}	–	Ω
C_f	Floating Capacitance	$V = 0, f = 1\text{MHz}$	–	0.6	1	pF

Note:

- Current Transfer Ratio (CTR) = $I_C/I_F \times 100\%$.

Typical Electrical/Optical Characteristic Curves ($T_A = 25^\circ\text{C}$ Unless otherwise specified.)

Fig. 1 Forward Current vs. Ambient Temperature

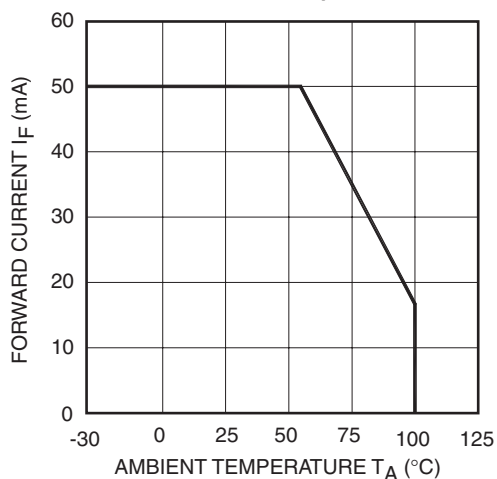


Fig. 2 Collector Power Dissipation vs. Ambient Temperature

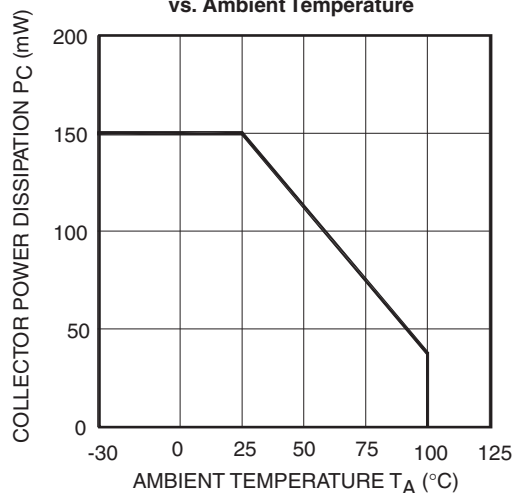


Fig. 3 Collector-Emitter Saturation Voltage vs. Forward Current

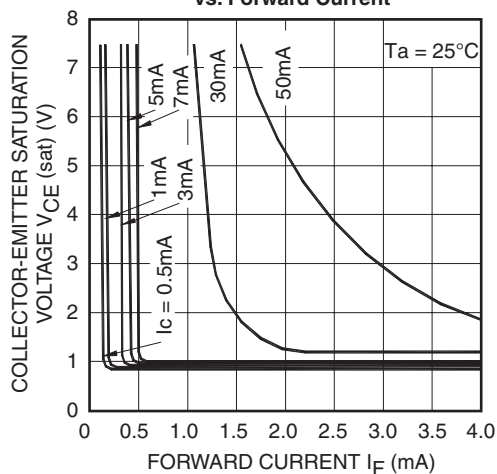


Fig. 4 Forward Current vs. Forward Voltage

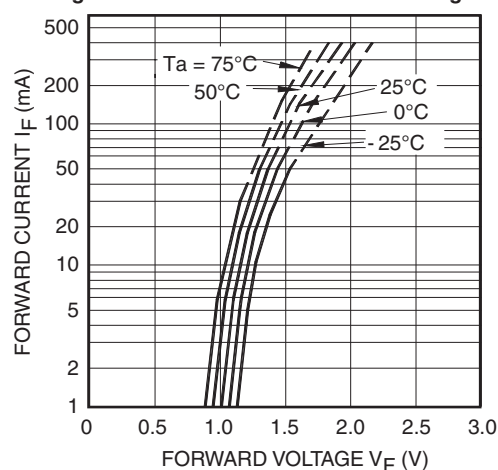


Fig. 5 Current Transfer Ratio vs. Forward Current

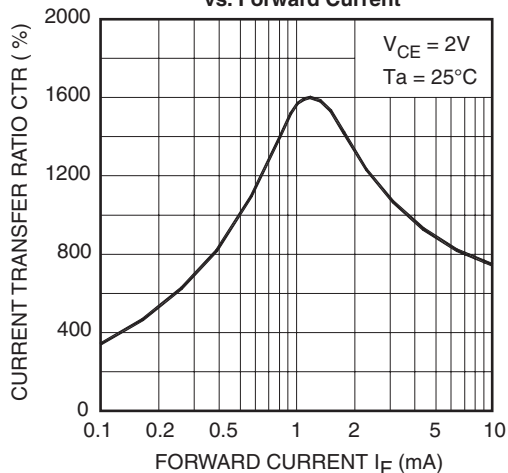
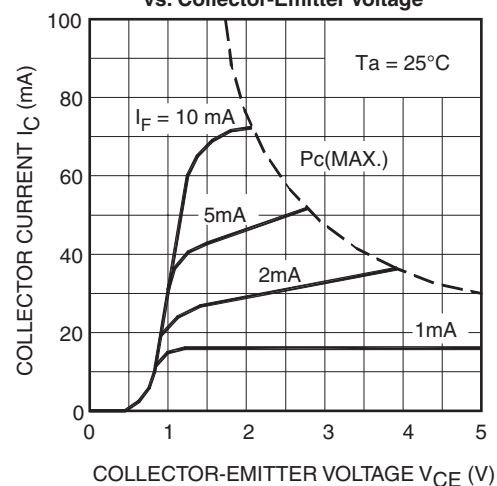


Fig. 6 Collector Current vs. Collector-Emitter Voltage



Typical Electrical/Optical Characteristic Curves ($T_A = 25^\circ\text{C}$ Unless otherwise specified.)

Fig. 7. Relative Current Transfer Ratio vs. Ambient Temperature

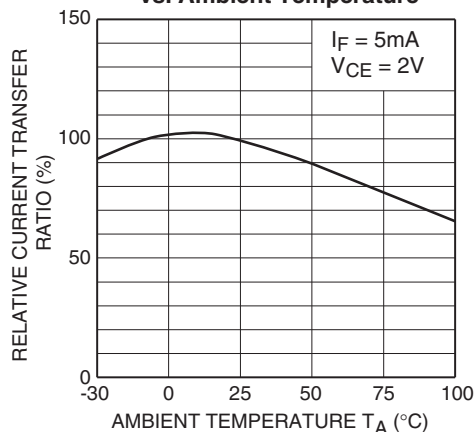


Fig. 8 Collector-Emitter Saturation Voltage vs. Ambient Temperature

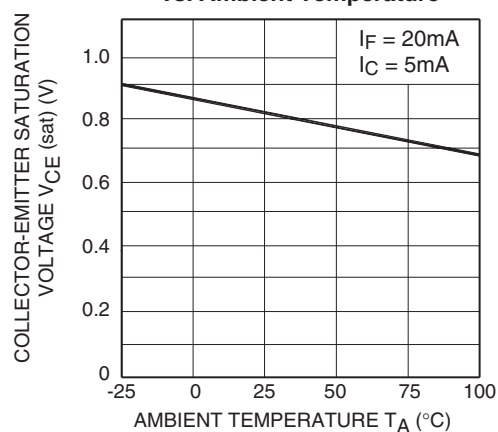


Fig. 9 Collector Dark Current vs. Ambient Temperature

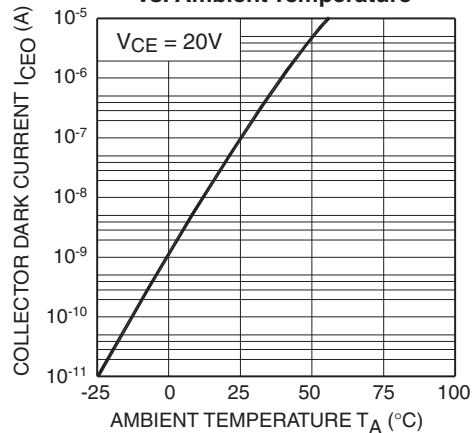


Fig. 10. Response Time vs. Load Resistance

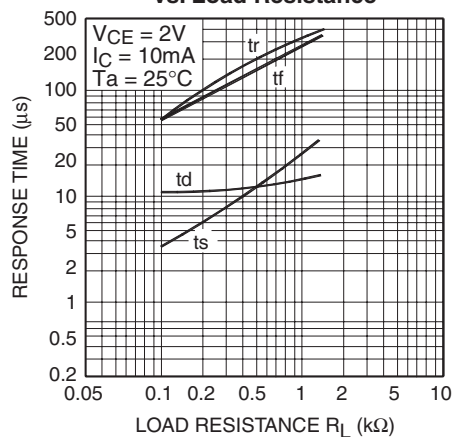
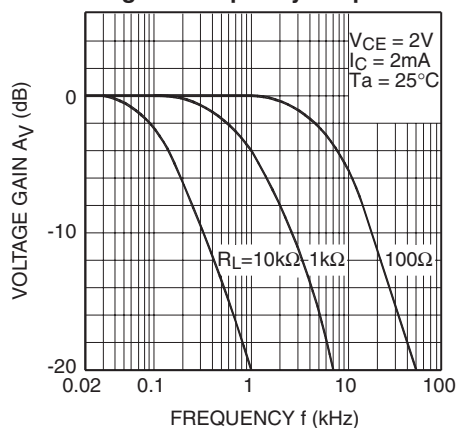
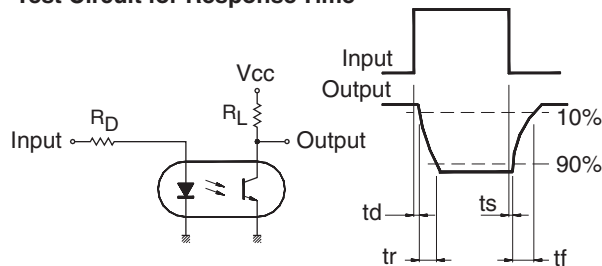


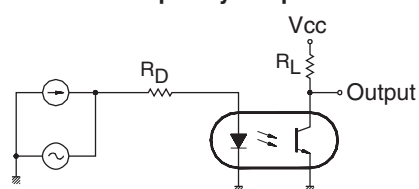
Fig. 11. Frequency Response



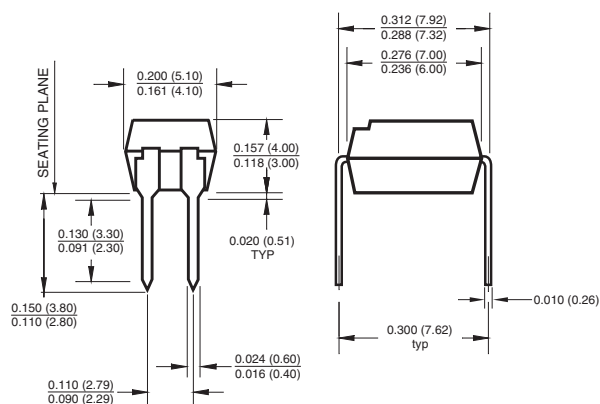
Test Circuit for Response Time



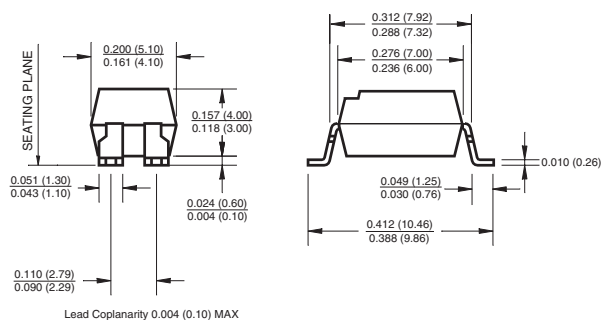
Test Circuit for Frequency Response



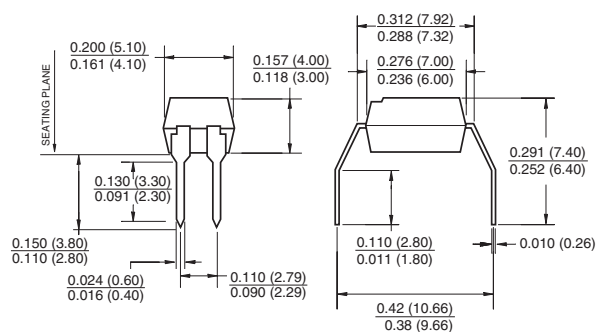
Package Dimensions (Through Hole)



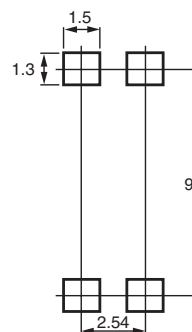
Package Dimensions (Surface Mount)



Package Dimensions (0.4" Lead Spacing)



Footprint Dimensions (Surface Mount)



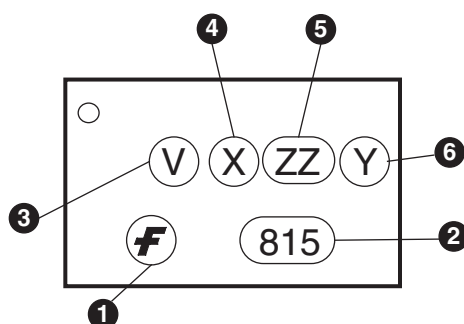
Note:

All dimensions are in inches (millimeters)

Ordering Information

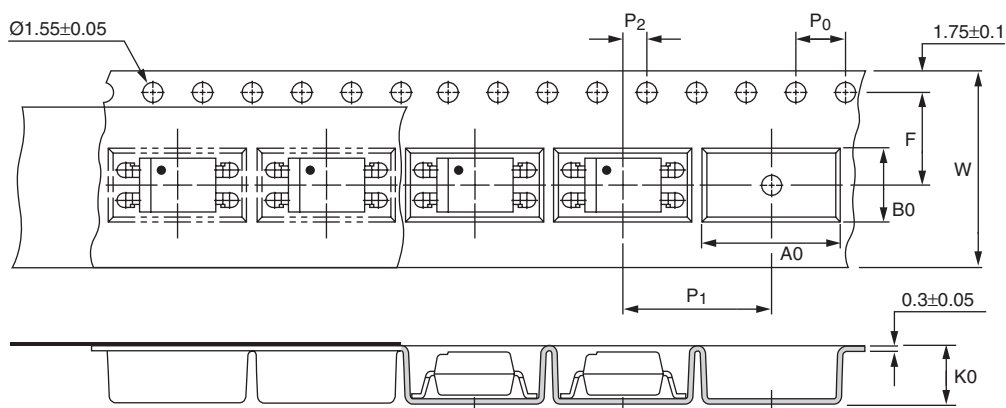
Option	Order Entry Identifier	Description
S	.S	Surface Mount Lead Bend
SD	.SD	Surface Mount; Tape and reel
W	.W	0.4" Lead Spacing
300	.300	VDE Approved
300W	.300W	VDE Approved, 0.4" Lead Spacing
3S	.3S	VDE Approved, Surface Mount
3SD	.3SD	VDE Approved, Surface Mount, Tape & Reel

Marking Information



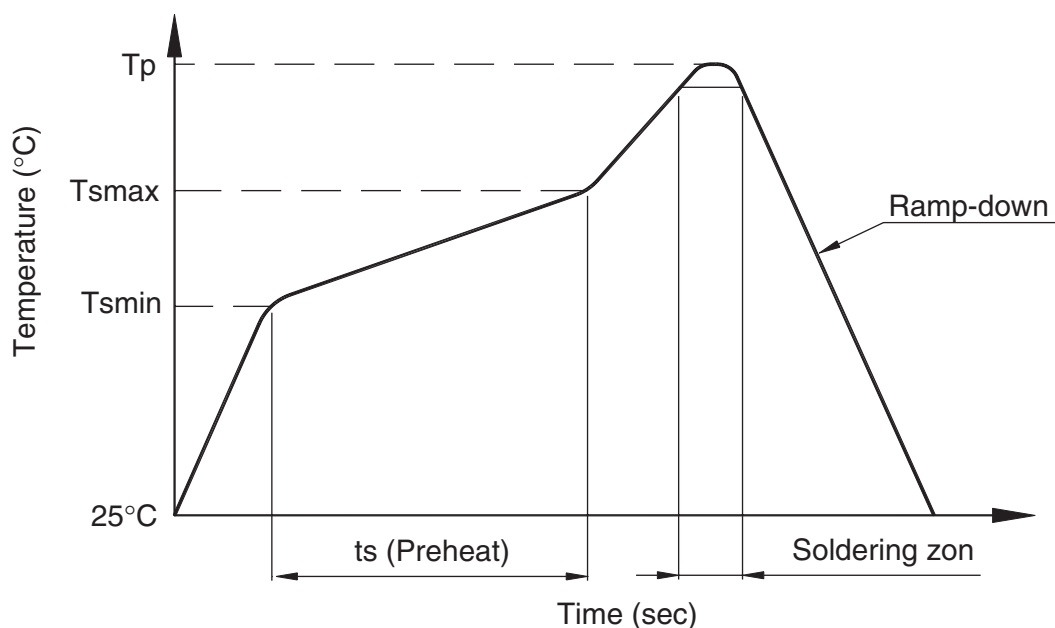
Definitions	
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	One digit year code
5	Two digit work week ranging from '01' to '53'
6	Assembly package code

Carrier Tape Specifications


Note:

All dimensions are in millimeters.

Description	Symbol	Dimensions in mm (inches)
Tape wide	W	16 ± 0.3 (.63)
Pitch of sprocket holes	P ₀	4 ± 0.1 (.15)
Distance of compartment	F	7.5 ± 0.1 (.295)
	P ₂	2 ± 0.1 (.079)
Distance of compartment to compartment	P ₁	12 ± 0.1 (.472)
Compartment	A0	10.45 ± 0.1 (.411)
	B0	5.30 ± 0.1 (.209)
	K0	4.25 ± 0.1 (.167)

Lead Free Recommended IR Reflow Condition

Profile Feature	Pb-Sn solder assembly	Lead Free assembly
Preheat condition (Tsmín-Tsmáx / ts)	100°C ~ 150°C 60 ~ 120 sec	150°C ~ 200°C 60 ~ 120 sec
Melt soldering zone	183°C 60 ~ 120 sec	217°C 30 ~ 90 sec
Peak temperature (Tp)	240 +0/-5°C	260 +0/-5°C
Ramp-down rate	6°C/sec max.	6°C/sec max.

Recommended Wave Soldering condition

Profile Feature	For all solder assembly
Peak temperature (Tp)	Max 260°C for 10 sec

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Build it Now™	FRFET™	MicroFET™	QFET®	SuperSOT™-8
CoolFET™	GlobalOptoisolator™	MicroPak™	QS™	SyncFET™
CROSSVOLT™	GTO™	MICROWIRE™	QT Optoelectronics™	TCM™
DOVE™	HiSeC™	MSX™	Quiet Series™	TinyLogic®
EcoSPARK™	I ² C™	MSXPro™	RapidConfigure™	TINYOPTO™
E ² C MOS™	i-Lo™	OCX™	RapidConnect™	TruTranslation™
EnSigna™	ImpliedDisconnect™	OCXPro™	μSerDes™	UHC™
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FACT Quiet Series™		OPTOPLANAR™	SILENT SWITCHER®	UltraFET®
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PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
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Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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